Analog Devices Welcomes Hittite Microwave Corporation

NO CONTENT ON THE ATTACHED DOCUMENT HAS CHANGED

www.analog.com www.hittite.com
LP6 (E) – 6 x 6 mm QUAD FLATPACK NO-LEAD (QFN) PLASTIC PACKAGE

**LP6 (E) Package Outline Drawing**

![LP6 (E) Package Outline Drawing](image)

**Notes:**
1. LEADFRAME MATERIAL: COPPER ALLOY
2. DIMENSIONS ARE IN INCHES [MILLIMETERS]
3. PAD SPACING TOLERANCE IS NON-CUMULATIVE
4. PAD BURR LENGTH SHALL BE 0.15mm MAXIMUM.
   PAD BURR HEIGHT SHALL BE 0.05mm MAXIMUM.
5. PACKAGE WARP SHALL NOT EXCEED 0.05mm.
6. ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO PCB RF GROUND.
7. REFER TO HITTITE APPLICATION NOTE FOR SUGGESTED LAND PATTERN.

**Package Information**

<table>
<thead>
<tr>
<th>Part Number Suffix</th>
<th>Package Body Material</th>
<th>Lead Finish</th>
<th>MSL Rating</th>
<th>Package Marking [3][4]</th>
</tr>
</thead>
<tbody>
<tr>
<td>LP6</td>
<td>RoHS Compliant Mold Compound</td>
<td>Sn/Pb Solder</td>
<td>MSL1 [1]</td>
<td>HNNN XXXX</td>
</tr>
<tr>
<td>LP6E</td>
<td>RoHS Compliant Mold Compound</td>
<td>100% matte Sn</td>
<td>MSL1 [2]</td>
<td>HNNN XXXX</td>
</tr>
</tbody>
</table>

[1] Max peak reflow temperature of 235 °C
[3] 4-Digit lot number XXXX
[4] 3-Digit part number NNN
NOTES:
1. DIMENSIONS ARE IN INCHES [MILLIMETERS].
2. PAD WIDTH SHOWN IS FOR SOLDERING ONLY. BEYOND SOLDERING AREA ALL CONDUCTORS THAT CARRY RF AND MICROWAVE SIGNALS SHOULD HAVE 50 OHM CHARACTERISTIC IMPEDANCE.
3. SOLDERMASK ON FAR SIDE SHOULD TENT OR PLUG VIA HOLES.
LP6C (E) – 6 x 6 mm QUAD FLATPACK NO-LEAD (QFN) PLASTIC PACKAGE

LP6C (E) Package Outline Drawing

NOTES:
1. PACKAGE BODY MATERIAL: LOW STRESS INJECTION MOLDED PLASTIC SILICA AND SILICON IMPREGNATED.
2. LEAD AND GROUND PADDLE MATERIAL: COPPER ALLOY.
3. LEAD AND GROUND PADDLE PLATING: 100% MATTE TIN.
4. DIMENSIONS ARE IN INCHES [MILLIMETERS].
5. LEAD SPACING TOLERANCE IS NON-CUMULATIVE.
6. PAD BURR LENGTH SHALL BE 0.15mm MAX. PAD BURR HEIGHT SHALL BE 0.25mm MAX.
7. PACKAGE WARP SHALL NOT EXCEED 0.05mm
8. ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO PCB RF GROUND.
9. REFER TO HITTITE APPLICATION NOTE FOR SUGGESTED PCB LAND PATTERN.

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<tbody>
<tr>
<td>LP6C</td>
<td>RoHS Compliant Mold Compound</td>
<td>Sn/Pb Solder</td>
<td>MSL1 [1]</td>
<td>HNNN XXXX</td>
</tr>
<tr>
<td>LP6CE</td>
<td>RoHS Compliant Mold Compound</td>
<td>100% matte Sn</td>
<td>MSL1 [2]</td>
<td>HNNN XXXX</td>
</tr>
</tbody>
</table>

[1] Max peak reflow temperature of 235 °C
[3] 4-Digit lot number XXXX
[4] 3-Digit part number NNN

For price, delivery, and to place orders, please contact Hittite Microwave Corporation:
20 Alpha Road, Chelmsford, MA 01824 Phone: 978-250-3343 Fax: 978-250-3373
Order On-line at www.hittite.com
Suggested LP6C (E) PCB Land Pattern

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